

## PRODUCT SPECIFICATION

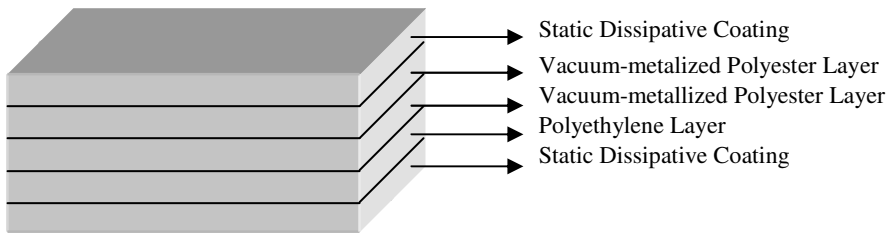
DOCUMENT CONTROL NO.: DY3008-652 REV. G

### DY3008-652 Moisture Barrier Material

**PRODUCT** : Moisture Barrier Film (Bag)

**DESCRIPTION** : -652 is 3.6mil, heat sealable, electro static protective, moisture protective multi-layer laminated material for ESD safe and moisture barrier packaging. DY3800 denotes “clean room grade”.

**CONSTRUCTION:** (from outer to inner layer in bag form)



Static Control



Cleanroom



Wafer Handling & Singulation



Electronics / Dry Packaging



IC Mold Cleaning Compound



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PHYSICAL PROPERTIES	TEST METHOD	TYPICAL VALUE
Total Thickness	ASTM D-374	3.6 mils ± 10%
Tensile Strength	ASTM D-882-91, Method A	> 7,000 psi (MD) > 7,000 psi (TD)
Tear Strength	ASTM D-1004-94 Notched	> 2.4 lbs (MD) > 2.7 lbs (TD)
Puncture Strength	FTMS 101C, Method 2065.1	≥ 20 lbs
Heat Seal Strength	ASTM D-882-91	≥ 14 lbs/in. width
MVTR (100 in <sup>2</sup> /24 hrs)	ASTM F-1249-90@100F	< 0.02 gm

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ELECTRICAL PROPERTIES	TEST METHOD	TYPICAL VALUE
Surface Resistance – Outer Surface	ANSI ESD-STM-11.11 @12% R.H.	<10 <sup>11</sup> Ω.
Surface Resistance – Inner Surface	ANSI ESD-STM-11.11 @12% R.H.	<10 <sup>11</sup> Ω.
Static Decay (12% RH, 5000 to 0 Volts)	FTMS 101 Mtd 4046	< 0.1 sec
Static Shielding	ESD-STM-11.31 @ 12% R.H.	< 10 nJ (*)

(\*) Certain bag configurations do not meet such criteria

**HEAT SEAL CONDITIONS** : 250°F -375°F, 0.8-3.5 sec, 30-70 PSI.

The values shown above were developed from random samples taken from production material. We believe them to be typical for the product. Actual values may vary somewhat from those depicted here and Dou Yee Enterprises makes no warranty, expressed or implied, as to the suitability of these materials for any specific use. Customers should determine product suitability based upon their own criteria and further qualification process.

Date : November 2013



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